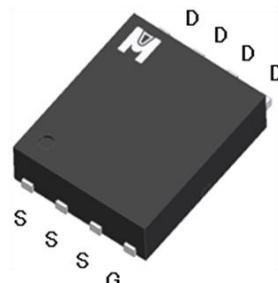
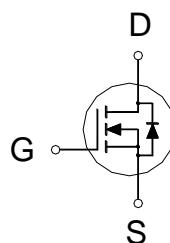


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV_{DSS}	80V
$R_{DS(on)}$ (MAX.)	$12.8\text{m}\Omega$
I_D	47A



UIS, Rg 100% Tested

RoHS & Halogen Free & TSCA Compliant



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 30	V
Continuous Drain Current	$T_C = 25^\circ\text{C}$	I_D	47	A
	$T_C = 100^\circ\text{C}$		27	
Pulsed Drain Current ^{1,3}		I_{DM}	150	
Avalanche Current		I_{AS}	30	
Avalanche Energy	$L = 0.1\text{mH}, I_D=30\text{A}, R_G=25\Omega$	E_{AS}	45	mJ
Repetitive Avalanche Energy ²	$L = 0.05\text{mH}$	E_{AR}	22.5	
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	50	W
	$T_C = 100^\circ\text{C}$		20	
Operating Junction & Storage Temperature Range		T_j, T_{stg}	-55 to 150	°C

100% UIS testing in condition of $VD=40\text{V}$, $L=0.1\text{mH}$, $VG=10\text{V}$, $IL=18\text{A}$, Rated $VDS=80\text{V}$ N-CH

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		2.5	°C / W
Junction-to-Ambient	$R_{\theta JA}$		75	

¹Pulse width limited by maximum junction temperature.

²Duty cycle < 1%

³The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz.

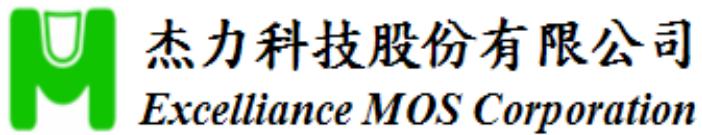
Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

⁴Guarantee by Engineering test

ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	80			V
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	2	3	4	
Gate-Body Leakage	I_{GSS}	$V_{\text{DS}} = 0\text{V}, V_{\text{GS}} = \pm 30\text{V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}} = 64\text{V}, V_{\text{GS}} = 0\text{V}$			1	μA
		$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}, T_J = 125^\circ\text{C}$			25	
On-State Drain Current ¹	$I_{\text{D}(\text{ON})}$	$V_{\text{DS}} = 10\text{V}, V_{\text{GS}} = 10\text{V}$	47			A
Drain-Source On-State Resistance ¹	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		10.8	12.8	$\text{m}\Omega$
Forward Transconductance ¹	g_{fs}	$V_{\text{DS}} = 5\text{V}, I_D = 20\text{A}$		36		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 40\text{V}, f = 1\text{MHz}$		1683		pF
Output Capacitance	C_{oss}			204		
Reverse Transfer Capacitance	C_{rss}			29		
Gate Resistance	R_g	$V_{\text{GS}} = 15\text{mV}, V_{\text{DS}} = 0\text{V}, f = 1\text{MHz}$		2.2		Ω
Total Gate Charge ^{1,2}	Q_g	$V_{\text{DS}} = 40\text{V}, V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		21		nC
Gate-Source Charge ^{1,2}	Q_{gs}			10		
Gate-Drain Charge ^{1,2}	Q_{gd}			5		
Turn-On Delay Time ^{1,2}	$t_{\text{d}(\text{on})}$	$V_{\text{DS}} = 40\text{V}, I_D = 5\text{A}, V_{\text{GS}} = 10\text{V}, R_G = 6\Omega$		25		nS
Rise Time ^{1,2}	t_r			90		
Turn-Off Delay Time ^{1,2}	$t_{\text{d}(\text{off})}$			80		
Fall Time ^{1,2}	t_f			110		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_C = 25^\circ\text{C}$)						
Continuous Current	I_S				47	A
Pulsed Current ³	I_{SM}				150	
Forward Voltage ¹	V_{SD}	$I_F = 20\text{A}, V_{\text{GS}} = 0\text{V}$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F = 20\text{A}, dI_F/dt = 100\text{A}/\mu\text{s}$		110		nS
Reverse Recovery Charge	Q_{rr}			320		nC

¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.²Independent of operating temperature.³Pulse width limited by maximum junction temperature.



EMD16N08H

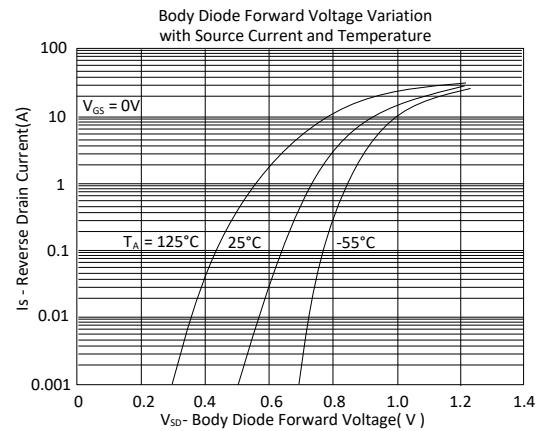
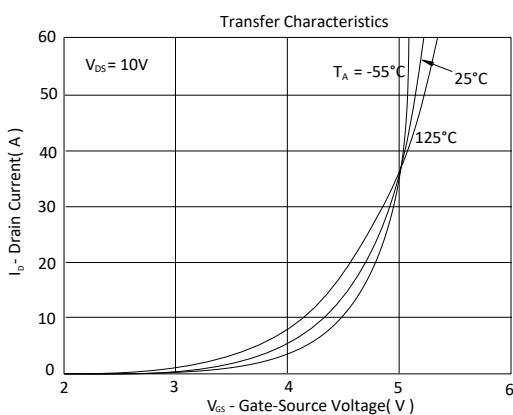
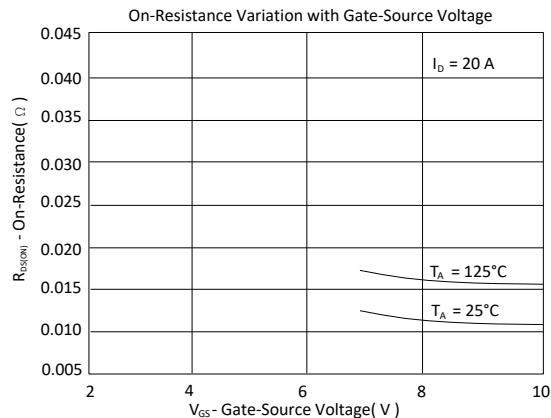
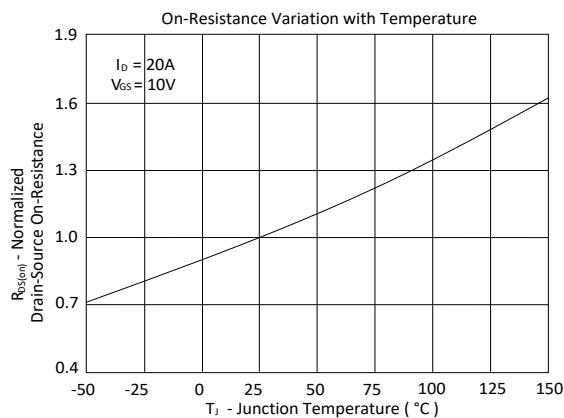
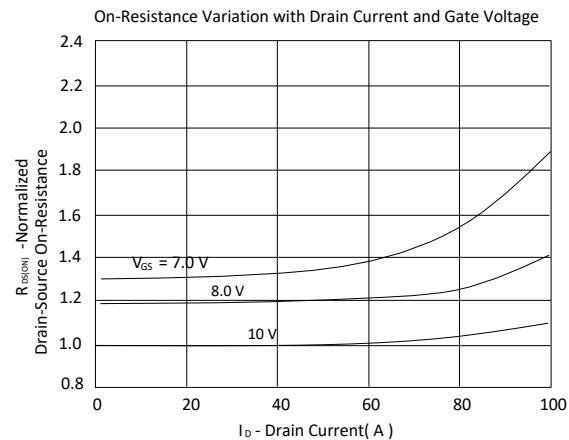
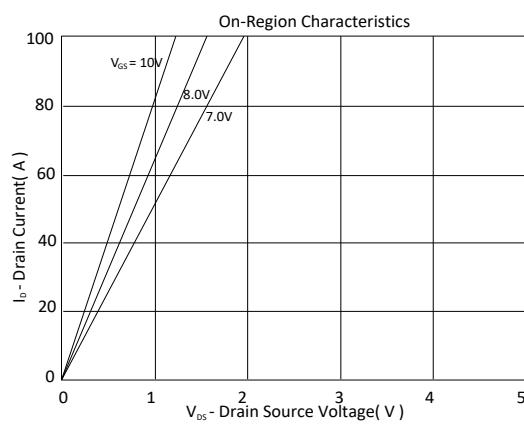
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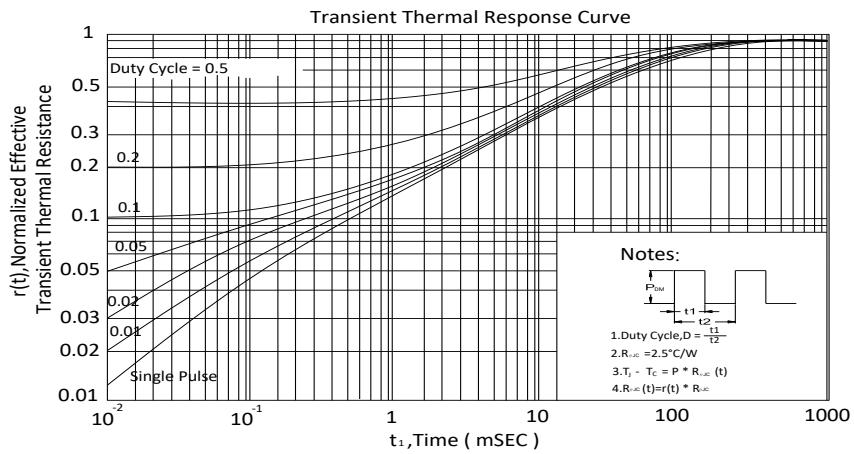
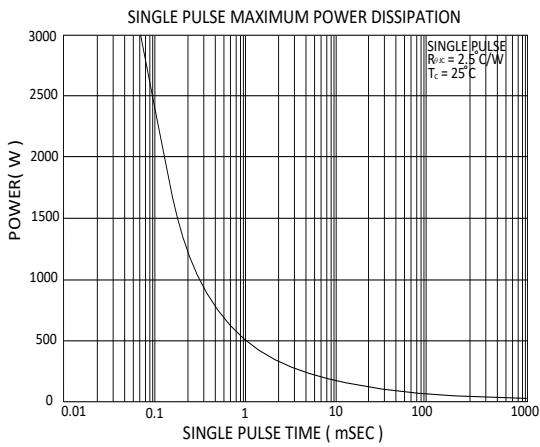
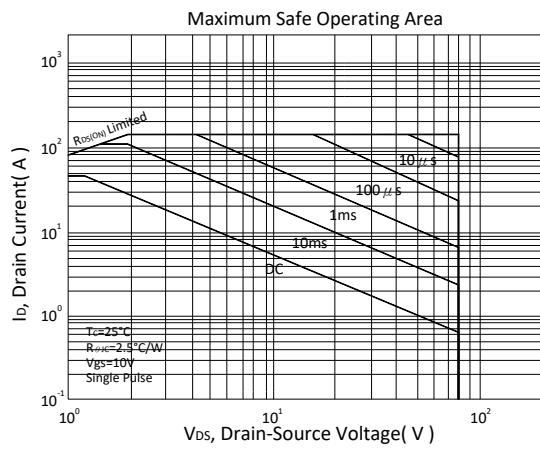
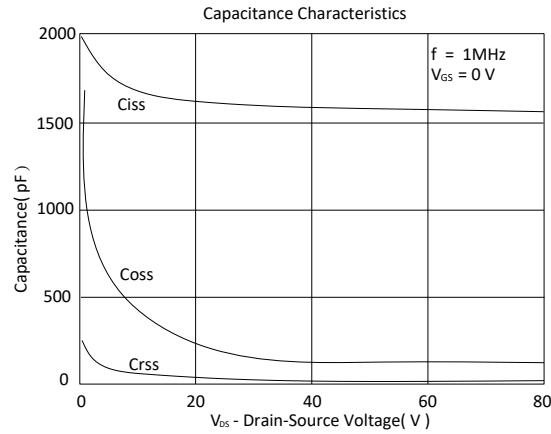
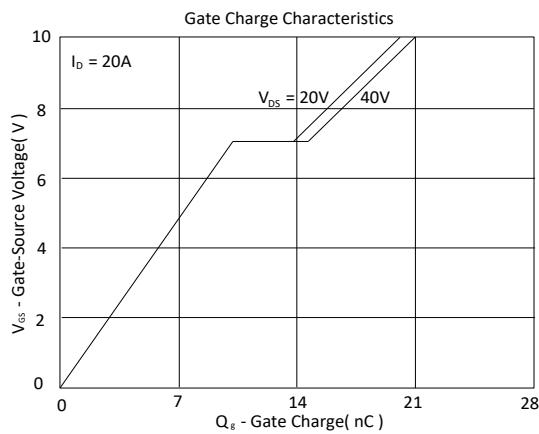
Device Name: EMD16N08H for EDFN 5 x 6



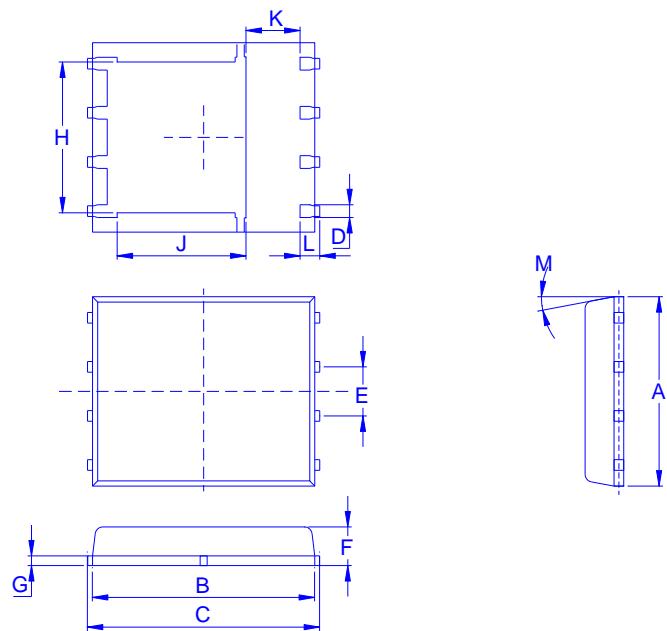
- D16N08: Device Name
- ABCDEFG: Date Code
- A: Assembly House
- B: Year(A:2008 B:2009 C:2010....)
- C: Month(A:01 B:02 C:03 D:04 E:05 F:06 G:07 H:08 I:09 J:10 K:11 L:12)
- DEFG: Serial No.

TYPICAL CHARACTERISTICS





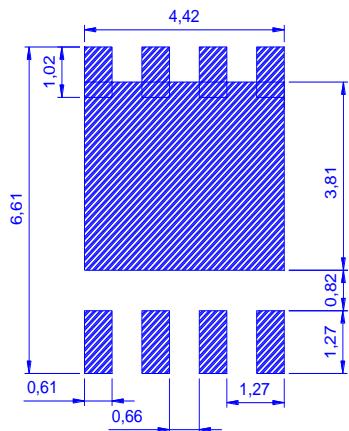
Outline Drawing



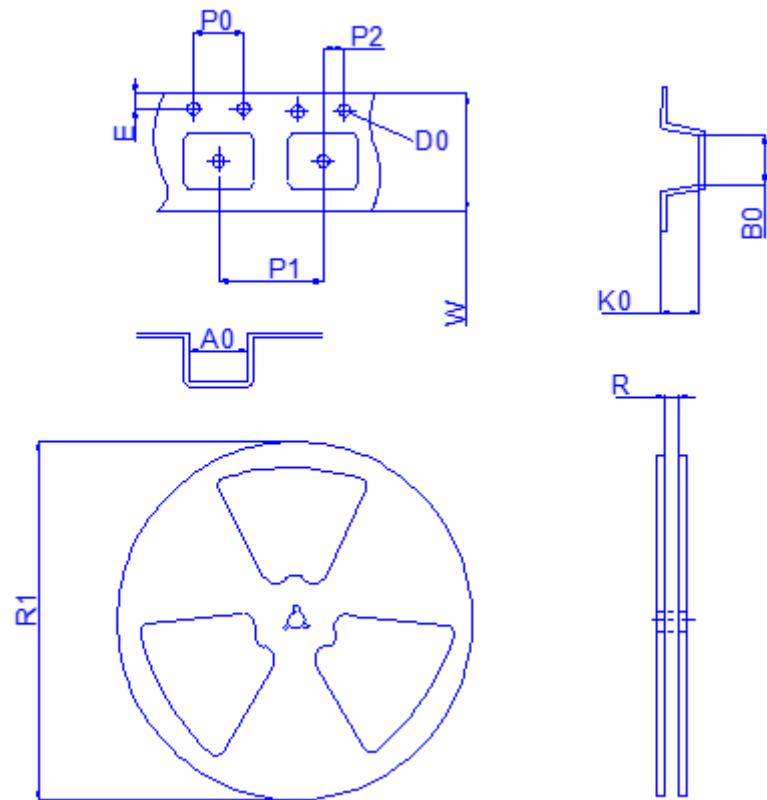
Dimension in mm

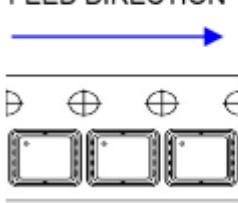
Dimension	A	B	C	D	E	F	G	H	J	K	L	M
Min	4.8	5.55	5.9	0.3	1.17	0.85	0.15	3.61	3.18	1	0.38	0°
Typ.	4.9	5.7	6	0.4	1.27	0.95	0.2	3.87	3.44	1.2	0.4	
Max	5.4	5.85	6.15	0.51	1.37	1.17	0.34	4.31	3.78	1.39	0.71	12°

Recommended minimum pads



Tape&Reel Information:2500pcs/Reel



Package	EDFN5X6
Reel	13"
Device orientation	FEED DIRECTION 

Dimension in mm

Dimension	Carrier tape								W	R	R1
	A0	B0	D0	E	K0	P0	P1	P2			
Typ.	6.4	5.3	1.5	1.8	1.6	4	8	2	12	12.4	330
±	0.2	0.2	0.1	0.1	0.6	0.1	0.1	0.1	0.3	2	2